

METHOD FOR CHAMFERING WAFER

ABSTRACT

In a conventional wafer chamfering process, the chamfered shape (cross-sectional shape) of the wafer circumference is uniform. However, in the chamfering step in wafer manufacture, the uniform chamfered shape varies with respective circumferential positions. Therefore, a wafer chamfering method that takes into account deformation in the chamfering step in the wafer manufacture is to be provided. The wafer chamfering method is for chamfering a wafer by bringing a grooveless grindstone into contact with the edge (circumferential end) of a wafer. By this wafer chamfering method, a movement trajectory formed by moving the wafer and the grindstone in a relative manner in the Z-axis and Y-axis directions and forming the same cross-sectional shape on the entire wafer circumference is set as a reference. So as to perform a processing operation in which the relative positions of the wafer and the grindstone are changed from positions on the reference trajectory at least in one of the Z-axis and Y-axis directions depending on wafer rotation angle positions, different cross-sectional shapes are formed depending on the wafer rotation angle positions with the use of a piezoelectric actuator.

FIG. 15